

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hung-Sung PAN</td> <td>08/21/2012</td> </tr> <tr> <td>Wen-Chia WU</td> <td>08/21/2012</td> </tr> </tbody> </table>		Name	Execution Date	Hung-Sung PAN	08/21/2012	Wen-Chia WU	08/21/2012
Name	Execution Date						
Hung-Sung PAN	08/21/2012						
Wen-Chia WU	08/21/2012						
RECEIVING PARTY DATA							
Name:	HIWIN TECHNOLOGIES CORP.						
Street Address:	No.46, 37th Road, Taichung Industrial Park						
City:	Taichung						
State/Country:	TAIWAN						
Postal Code:	407						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13591227</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13591227		
Property Type	Number						
Application Number:	13591227						
CORRESPONDENCE DATA							
Fax Number:							
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>							
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ATTORNEY DOCKET NUMBER:	CFP-5147; C-974						
NAME OF SUBMITTER:	BANGER SHIA						
<p>Total Attachments: 3 source=CFP-5147- Assignment-deed#page1.tif source=CFP-5147- Assignment-deed#page2.tif source=CFP-5147- Assignment-deed#page3.tif</p>							

OP \$40.00 13591227

PATENT

ASSIGNMENT DEED

ASSIGNOR:

PAN, HUNG-SUNG
No.46, 37th Road, Taichung Industrial Park, Taichung 407, Taiwan, R.O.C.
WU, WEN-CHIA
No.46, 37th Road, Taichung Industrial Park, Taichung 407, Taiwan, R.O.C.

ASSIGNEE:

HIWIN TECHNOLOGIES CORP.
No.46, 37th Road, Taichung Industrial Park, Taichung 407, Taiwan, R.O.C.

Whereas, PAN, HUNG-SUNG and WU, WEN-CHIA
whose address is set forth above (hereinafter referred to as "Assignor", consideration of payment to it of the sum of Ten U.S. Dollars (U.S.\$10.00) and for other good and valuable consideration, receipt and sufficiency of which are acknowledged hereby; received from HIWIN TECHNOLOGIES CORP., whose address is set forth above (hereinafter referred to as "Assignee");

Assignor has sold, assigned, and conveyed and hereby does evidence such sale, assignment and conveyance unto said Assignee, its successors and/or assigns, Assignor's entire right, title and interest -----

(1) In and to an invention entitled _____
BALL SCREW WITH SECTIONAL CIRCULATING ASSEMBLIES

as described in United States Patent Application Serial No. _____, filed on _____; which issued into United States Letters Patent No. _____ on _____, including the right to recover for past infringements thereof.

(2) In and to said Application for Letters Patent and said Letters Patent No. _____ which issued _____ on said Application and any and all other applications for letters patent of the United States of America (including renewal, divisional, continuation, continuation-in-part, substitute and reissue applications) based upon said invention, including extensions and reissues, if any, to the full ends of the terms for which said Letters Patent of the United states has been granted.

(3) In and to all applications for said invention, now or hereafter filed in countries foreign to the United States of America, and in and to any and all letters patent granted on said applications to the full ends of the terms for which said Letters Patent may be granted.

Assignor further covenants and agrees that it has not executed and will not execute any documents in conflict herewith, and it further agrees that it will at any time upon request by Assignees execute and deliver any and all papers that may be necessary or desirable to perfect title to said invention, Application for Letters Patent, and the Letters Patent to Assignees, and if Assignees desires to file one or more divisional, continuation, continuation-in-part, or substitute applications of or for said Letters Patent of the United States of America, or to secure a reissue or extension of such Letters Patent, or to file a disclaimer relating thereto, Assignors will upon request by Assignees sign all papers, make all rightful oaths and do all lawful acts requisite of it for such reissue or extension, or the procuring thereof, and for the filing of such disclaimer, but at the expense of Assignees, its successors and/or assigns.

Assignor further agrees that it will at any time upon request by Assignee communicate to Assignee any facts relating to said invention and Letters Patent or the history thereof, know to Assignor and cause its agent(s) to testify to the same in any interference or any litigation when requested so to do by Assignee.

And the Commissioner of Patents and Trademarks of the United States of America and comparable officials in countries foreign to the United States of America to record and/or issue said Letters Patent, and the like to Assignee as assignee of Assignor's entire right, title and interest therein.

Signed at Taichung, Taiwan this 21th day of August, 2012.

Assignor:

By : Pan, Hung-Sung Wu, Wen Chia _____

Name : PAN, HUNG-SUNG

WU, WEN-CHIA _____

Title : Inventors

Date : August 21, 2012

Witness:

Signature: _____

Name :

Address :

Date: